

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	22	("4575700" "5426399" "5429978" "5447887" "5849625" "5986331" "6140688" "6255698" "6259407" "6407441" "6756673").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:38
L2	1211	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:38
L3	2511	coplanar with waveguide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:42
L4	75	2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:38
L5	1387	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:42
L6	2	5 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:43
L7	1151	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:43
L8	3	3 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:44
L9	752	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:44

L11	1	9 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:44
L12	983	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:44
L13	83	12 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:46
L14	406	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:46
L16	12	14 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:47
L17	731	(361/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:47
L18	0	17 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:48
L19	1733	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L20	54	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L21	8	((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L22	1124	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L23	274	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L24	47	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L25	6	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L26	77	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L27	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L28	33	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L29	12	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L30	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L31	25	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L32	891	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L33	822	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L34	44	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L35	102	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L36	313	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L37	305	signal with line and ground with line and 438/6\$2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L38	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/08/19 12:49
L39	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/08/19 12:49
L40	220	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L41	145	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49

L42	390	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L43	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/08/19 12:49
L44	207	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L45	2437	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L46	1364	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L47	694	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L48	89	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L49	94	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L50	1523	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L51	794	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L52	161	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L53	4868	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L54	401	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L55	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L56	681	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L57	418	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L58	92	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L59	1059	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L60	663	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L61	507	((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L62	4	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L63	465	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L64	231	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L65	196	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L66	86	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L67	1546	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L68	943	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L69	616	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L70	551	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L71	6	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L72	177	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L73	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L74	10934	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L75	108	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L76	7600	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L77	3533	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L78	200	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L79	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/08/19 12:49
L80	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/08/19 12:49
L81	31	"5903053".URPN.	USPAT	OR	ON	2005/08/19 12:49
L82	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/08/19 12:49
L83	5	"5705857".URPN.	USPAT	OR	ON	2005/08/19 12:49
L84	14	"5429978".URPN.	USPAT	OR	ON	2005/08/19 12:49
L85	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/08/19 12:49
L86	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L87	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/08/19 12:49
L88	24	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L89	21	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L90	21	"5909044".URPN.	USPAT	OR	ON	2005/08/19 12:49
L91	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L92	8	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L93	1038	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L94	389	waveguide with trench	USPAT	OR	ON	2005/08/19 12:49
L95	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/08/19 12:49
L96	3	"5783844".URPN.	USPAT	OR	ON	2005/08/19 12:49
L97	119	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/08/19 12:49
L98	193	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/08/19 12:49
L99	90	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/08/19 12:49
L100	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/08/19 12:49
L101	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/08/19 12:49
L102	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/08/19 12:49
L103	183	gate with polysilicon with copper	USPAT	OR	ON	2005/08/19 12:49
L104	3914	silicide with silicon with nitride	USPAT	OR	ON	2005/08/19 12:49

L105	2133	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:49
L106	982	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/08/19 12:49
L107	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/08/19 12:49
L108	3	silicide with spacer with copper	USPAT	OR	ON	2005/08/19 12:49
L109	0	silicide with copper and sinane	USPAT	OR	ON	2005/08/19 12:49
L110	295	silicide with copper and silane	USPAT	OR	ON	2005/08/19 12:49
L111	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/08/19 12:49
L112	24	copper with silicide and 438/655.ccls.	USPAT	OR	ON	2005/08/19 12:49
L113	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/08/19 12:49
L114	1	"5,447,887".pn.	USPAT	OR	ON	2005/08/19 12:49
L115	1	"6255698".pn.	USPAT	OR	ON	2005/08/19 12:49
L116	513	thermal with evaporation with CVD	USPAT	OR	ON	2005/08/19 12:49
L117	182	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:49
L118	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:49
L119	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:49
L120	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/08/19 12:49
L121	1	"6255698".pn.	USPAT	OR	ON	2005/08/19 12:49
L122	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/08/19 12:49
L123	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/08/19 12:49
L124	9	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/08/19 12:49
L125	23	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/08/19 12:49
L126	141	trench with etch\$5 with improve	USPAT	OR	ON	2005/08/19 12:49
L127	881	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/08/19 12:49
L128	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/08/19 12:49
L129	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/08/19 12:49
L130	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/08/19 12:49
L131	191	trench with etch\$5 with commonly	USPAT	OR	ON	2005/08/19 12:49
L132	1	"4631803".pn.	USPAT	OR	ON	2005/08/19 12:49

L133	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L134	767	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L135	151	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L136	255	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L137	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/08/19 12:49
L138	23	"5424693".URPN.	USPAT	OR	ON	2005/08/19 12:49
L139	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/08/19 12:49
L140	983	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L141	198	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L142	175	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L143	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/08/19 12:49
L144	8	"5652557".URPN.	USPAT	OR	ON	2005/08/19 12:49
L145	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/08/19 12:49
L146	25	"5426399".URPN.	USPAT	OR	ON	2005/08/19 12:49
L147	4	"4607240".URPN.	USPAT	OR	ON	2005/08/19 12:49

L148	406	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L149	30	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L150	289	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L151	259	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L152	146	(((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L153	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L154	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L155	9	"3975690".URPN.	USPAT	OR	ON	2005/08/19 12:49
L156	5	"4322695".URPN.	USPAT	OR	ON	2005/08/19 12:49
L157	5	"5519363".URPN.	USPAT	OR	ON	2005/08/19 12:49
L158	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/08/19 12:49
L159	1211	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:49
L160	234	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49

L161	219	((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L162	200	((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:49
L163	8	"4575700".URPN.	USPAT	OR	ON	2005/08/19 12:49
L164	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/08/19 12:49
L165	15	"4379307".URPN.	USPAT	OR	ON	2005/08/19 12:49
L166	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/08/19 12:49
L167	4	"5512776".URPN.	USPAT	OR	ON	2005/08/19 12:49
L168	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/08/19 12:49
L169	4	"5012319".URPN.	USPAT	OR	ON	2005/08/19 12:49
L170	4	"5012319".URPN.	USPAT	OR	ON	2005/08/19 12:49
L171	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/08/19 12:49
L172	18465	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L173	559	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L174	286	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L175	2413	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L176	1010	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L177	989	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L178	21158	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L179	53	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L180	10	"4554567".URPN.	USPAT	OR	ON	2005/08/19 12:50
L181	609	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L182	1257541	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L183	7	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L184	524	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L185	8	"4575700".URPN.	USPAT	OR	ON	2005/08/19 12:50
L186	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/08/19 12:50
L187	28	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L188	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L189	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L190	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L191	1387	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L192	500	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L193	752	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L194	1151	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L195	3	(L190 or L191 or L193 or L194 or L192) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L196	0	(L190 or L191 or L193 or L194 or L192) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L197	24	(L190 or L191 or L193 or L194 or L192) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L198	1733	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L199	1124	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L200	274	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L201	47	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L202	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L203	891	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L204	822	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L205	2437	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L206	1364	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L207	694	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L208	1523	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L209	794	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L210	4868	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L211	1059	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L212	663	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L213	507	((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L214	465	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L215	196	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L216	1546	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L217	943	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L218	616	((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L219	551	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L220	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L221	10934	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L222	7600	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L223	3533	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L224	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L225	21	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L226	193	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/08/19 12:50
L227	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/08/19 12:50
L228	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/08/19 12:50
L229	3914	silicide with silicon with nitride	USPAT	OR	ON	2005/08/19 12:50
L230	2133	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:50
L231	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/08/19 12:50
L232	0	silicide with copper and silane	USPAT	OR	ON	2005/08/19 12:50
L233	295	silicide with copper and silane	USPAT	OR	ON	2005/08/19 12:50
L234	513	thermal with evaporation with CVD	USPAT	OR	ON	2005/08/19 12:50
L235	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:50
L236	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/08/19 12:50
L237	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/08/19 12:50
L238	881	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/08/19 12:50
L239	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/08/19 12:50

L240	767	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L241	983	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L242	198	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L243	406	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L244	259	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L245	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L246	1211	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L247	234	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L248	219	(((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L249	18465	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L250	559	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L251	2413	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L252	1010	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L253	989	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L254	21158	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L255	609	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L256	1257541	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON AJD OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L257	28	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L258	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L259	1387	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L260	500	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L261	752	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50

L262	1151	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L263	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L264	3	(L263 or L259 or L261 or L262 or L260) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L265	0	(L263 or L259 or L261 or L262 or L260) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L266	1	"5,447,887".pn.	USPAT	OR	ON	2005/08/19 12:50
L267	1	"6255698".pn.	USPAT	OR	ON	2005/08/19 12:50
L268	1	"6255698".pn.	USPAT	OR	ON	2005/08/19 12:50
L269	1	"4631803".pn.	USPAT	OR	ON	2005/08/19 12:50
L270	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L271	54	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L272	8	((((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L273	6	((((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and (((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and (((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L274	77	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L275	33	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L276	12	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L277	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L278	25	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L279	44	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L280	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/08/19 12:50
L281	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/08/19 12:50
L282	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/08/19 12:50
L283	89	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L284	94	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L285	92	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L286	4	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L287	86	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L288	6	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L289	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/08/19 12:50
L290	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/08/19 12:50
L291	31	"5903053".URPN.	USPAT	OR	ON	2005/08/19 12:50
L292	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/08/19 12:50
L293	5	"5705857".URPN.	USPAT	OR	ON	2005/08/19 12:50
L294	14	"5429978".URPN.	USPAT	OR	ON	2005/08/19 12:50
L295	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/08/19 12:50
L296	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/08/19 12:50
L297	24	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L298	21	"5909044".URPN.	USPAT	OR	ON	2005/08/19 12:50
L299	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L300	8	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L301	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/08/19 12:50
L302	3	"5783844".URPN.	USPAT	OR	ON	2005/08/19 12:50
L303	90	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/08/19 12:50
L304	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/08/19 12:50
L305	3	silicide with spacer with copper	USPAT	OR	ON	2005/08/19 12:50
L306	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/08/19 12:50
L307	24	copper with silicide and 438/655. ccls.	USPAT	OR	ON	2005/08/19 12:50
L308	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/08/19 12:50
L309	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:50
L310	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/08/19 12:50
L311	9	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/08/19 12:50
L312	23	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/08/19 12:50
L313	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/08/19 12:50
L314	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/08/19 12:50
L315	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L316	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/08/19 12:50
L317	23	"5424693".URPN.	USPAT	OR	ON	2005/08/19 12:50
L318	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/08/19 12:50
L319	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/08/19 12:50
L320	8	"5652557".URPN.	USPAT	OR	ON	2005/08/19 12:50
L321	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/08/19 12:50
L322	25	"5426399".URPN.	USPAT	OR	ON	2005/08/19 12:50
L323	4	"4607240".URPN.	USPAT	OR	ON	2005/08/19 12:50

L324	30	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L325	9	"3975690".URPN.	USPAT	OR	ON	2005/08/19 12:50
L326	5	"4322695".URPN.	USPAT	OR	ON	2005/08/19 12:50
L327	5	"5519363".URPN.	USPAT	OR	ON	2005/08/19 12:50
L328	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/08/19 12:50
L329	8	"4575700".URPN.	USPAT	OR	ON	2005/08/19 12:50
L330	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/08/19 12:50
L331	15	"4379307".URPN.	USPAT	OR	ON	2005/08/19 12:50
L332	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/08/19 12:50
L333	4	"5512776".URPN.	USPAT	OR	ON	2005/08/19 12:50
L334	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/08/19 12:50
L335	4	"5012319".URPN.	USPAT	OR	ON	2005/08/19 12:50
L336	4	"5012319".URPN.	USPAT	OR	ON	2005/08/19 12:50
L337	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/08/19 12:50
L338	53	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L339	10	"4554567".URPN.	USPAT	OR	ON	2005/08/19 12:50
L340	7	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L341	8	"4575700".URPN.	USPAT	OR	ON	2005/08/19 12:50
L342	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/08/19 12:50
L343	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50

L344	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L345	24	(L263 or L259 or L261 or L262 or L260) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L346	102	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L347	145	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L348	161	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L349	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:50
L350	177	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L351	108	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L353	200	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L354	119	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/08/19 12:50
L355	183	gate with polysilicon with copper	USPAT	OR	ON	2005/08/19 12:50
L356	182	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/08/19 12:50
L357	141	trench with etch\$5 with improve	USPAT	OR	ON	2005/08/19 12:50
L358	191	trench with etch\$5 with commonly	USPAT	OR	ON	2005/08/19 12:50

L359	151	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L360	175	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L361	146	((((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L362	200	(((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L363	220	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L364	207	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L365	231	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:50
L366	255	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L367	289	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L368	286	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L369	313	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51

L370	305	signal with line and ground with line and 438/6\$2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L371	390	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 12:51
L372	401	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L373	389	waveguide with trench	USPAT	OR	ON	2005/08/19 12:51
L374	418	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L375	524	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L376	681	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L377	982	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/08/19 12:51
L378	1038	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51
L379	2	"6756673".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 12:51

<i>Ref #</i>	<i>Hits</i>	<i>Search Query</i>	<i>DBs</i>	<i>Default Operator</i>	<i>Plurals</i>	<i>Time Stamp</i>
L388	109	(coplanar and waveguide and (trench via channel through hole)).clm.	US-PGPUB	OR	ON	2005/08/19 13:26